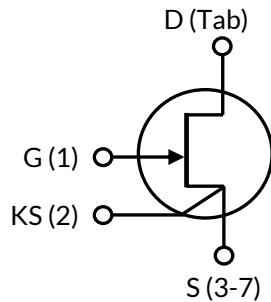
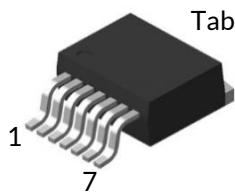


DATASHEET

UF3N170400B7S



| Part Number | Package | Marking |
|---------------|----------|---------------|
| UF3N170400B7S | D²PAK-7L | UF3N170400B7S |



1700V-400mΩ SiC Normally-on JFET

Preliminary, February 2020

Description

UnitedSiC offers the high-performance G3 SiC normally-on JFET transistors. This series exhibits ultra-low on resistance ($R_{DS(ON)}$) and gate charge (Q_G) allowing for low conduction and switching loss. The device normally-on characteristics with low $R_{DS(ON)}$ at $V_{GS} = 0$ V is also ideal for current protection circuits without the need for active control, as well as for cascode operation.

Features

- ◆ Typical on-resistance $R_{DS(on),typ}$ of 400mΩ
- ◆ Voltage controlled
- ◆ Maximum operating temperature of 175°C
- ◆ Extremely fast switching not dependent on temperature
- ◆ Low gate charge
- ◆ Low intrinsic capacitance
- ◆ RoHS compliant

Typical applications

- ◆ Over Current Protection Circuits
- ◆ DC-AC Inverters
- ◆ Switch mode power supplies
- ◆ Power factor correction modules
- ◆ Motor drives
- ◆ Induction heating

Maximum Ratings

| Parameter | Symbol | Test Conditions | Value | Units |
|---------------------------------------|----------------|---------------------------|------------|------------------|
| Drain-source voltage | V_{DS} | | 1700 | V |
| Gate-source voltage | V_{GS} | DC | -20 to +3 | V |
| | | AC ¹ | -30 to +20 | V |
| Continuous drain current ² | I_D | $T_C = 25^\circ\text{C}$ | 6.8 | A |
| | | $T_C = 100^\circ\text{C}$ | 5.1 | A |
| Pulsed drain current ³ | I_{DM} | $T_C = 25^\circ\text{C}$ | 16 | A |
| Power dissipation | P_{tot} | $T_C = 25^\circ\text{C}$ | 68 | W |
| Maximum junction temperature | $T_{J,max}$ | | 175 | $^\circ\text{C}$ |
| Operating and storage temperature | T_J, T_{STG} | | -55 to 175 | $^\circ\text{C}$ |
| Reflow soldering temperature | T_{solder} | reflow MSL 3 | 260 | $^\circ\text{C}$ |

1. +20V AC rating applies for turn-on pulses <200ns applied with external $R_G > 1\Omega$.

2. Limited by $T_{J,max}$

3. Pulse width t_p limited by $T_{J,max}$

Thermal Characteristics

| Parameter | Symbol | Test Conditions | Value | | | Units |
|--------------------------------------|----------------|-----------------|-------|-----|-----|---------------------------|
| | | | Min | Typ | Max | |
| Thermal resistance, junction-to-case | R_{\thetaJC} | | | 1.7 | 2.2 | $^\circ\text{C}/\text{W}$ |

Electrical Characteristics ($T_J = +25^\circ\text{C}$ unless otherwise specified)

Typical Performance - Static

| Parameter | Symbol | Test Conditions | Value | | | Units |
|--------------------------------|----------------------------|---|-------|------|-----|------------------|
| | | | Min | Typ | Max | |
| Drain-source breakdown voltage | BV_{DS} | $\text{V}_{\text{GS}}=-20\text{V}, \text{I}_D=0.3\text{mA}$ | 1700 | | | V |
| Total drain leakage current | I_{DSS} | $\text{V}_{\text{DS}}=1700\text{V}, \text{V}_{\text{GS}}=-20\text{V}, \text{T}_J=25^\circ\text{C}$ | | 2.2 | 60 | μA |
| | | $\text{V}_{\text{DS}}=1700\text{V}, \text{V}_{\text{GS}}=-20\text{V}, \text{T}_J=175^\circ\text{C}$ | | 9 | | |
| Total gate leakage current | I_{GSS} | $\text{V}_{\text{GS}}=-20\text{V}, \text{T}_J=25^\circ\text{C}$ | | 0.15 | 6 | μA |
| | | $\text{V}_{\text{GS}}=-20\text{V}, \text{T}_J=175^\circ\text{C}$ | | 0.8 | | |
| Drain-source on-resistance | $\text{R}_{\text{DS(on)}}$ | $\text{V}_{\text{GS}}=2\text{V}, \text{I}_D=5\text{A}, \text{T}_J=25^\circ\text{C}$ | | 350 | | $\text{m}\Omega$ |
| | | $\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=5\text{A}, \text{T}_J=25^\circ\text{C}$ | | 400 | 500 | |
| | | $\text{V}_{\text{GS}}=2\text{V}, \text{I}_D=5\text{A}, \text{T}_J=175^\circ\text{C}$ | | 928 | | |
| | | $\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=5\text{A}, \text{T}_J=175^\circ\text{C}$ | | 1040 | | |
| Gate threshold voltage | $\text{V}_{\text{G(th)}}$ | $\text{V}_{\text{DS}}=5\text{V}, \text{I}_D=4.5\text{mA}$ | -14 | -9.5 | -6 | V |
| Gate resistance | R_G | f=1MHz, open drain | | 5 | | Ω |

Typical Performance - Dynamic

| Parameter | Symbol | Test Conditions | Value | | | Units |
|--|---------------|--|-------|------|-----|---------|
| | | | Min | Typ | Max | |
| Input capacitance | C_{iss} | $V_{DS}=100V, V_{GS}=-20V$ $f=100kHz$ | | 225 | | pF |
| Output capacitance | C_{oss} | | | 22 | | |
| Reverse transfer capacitance | C_{rss} | | | 18 | | |
| Effective output capacitance, energy related | $C_{oss(er)}$ | $V_{DS}=0V \text{ to } 1200V, V_{GS}=-20V$ | | 11.4 | | pF |
| C_{oss} stored energy | E_{oss} | $V_{DS}=1200V, V_{GS}=-20V$ | | 8.2 | | μJ |
| Total gate charge | Q_G | $V_{DS}=1200V, I_D=5A, V_{GS} = -18V \text{ to } 0V$ | | 30 | | nC |
| Gate-drain charge | Q_{GD} | | | 17 | | |
| Gate-source charge | Q_{GS} | | | 5 | | |
| Turn-on delay time | $t_{d(on)}$ | $V_{DS}=1200V, I_D=5A, \text{Gate Driver } =-18V \text{ to } 0V, R_G=1\Omega, \text{Inductive Load, FWD: 2x UJ3D1210TS in series, } T_J=25^\circ C$ | | 5 | | ns |
| Rise time | t_r | | | 19 | | |
| Turn-off delay time | $t_{d(off)}$ | | | 9 | | |
| Fall time | t_f | | | 37 | | |
| Turn-on energy | E_{ON} | | | 125 | | |
| Turn-off energy | E_{OFF} | | | 38 | | |
| Total switching energy | E_{TOTAL} | | | 163 | | |
| Turn-on delay time | $t_{d(on)}$ | $V_{DS}=1200V, I_D=5A, \text{Gate Driver } =-18V \text{ to } 0V, R_G=1\Omega, \text{Inductive Load, FWD: 2x UJ3D1210TS in series, } T_J=150^\circ C$ | | 5 | | ns |
| Rise time | t_r | | | 16 | | |
| Turn-off delay time | $t_{d(off)}$ | | | 8 | | |
| Fall time | t_f | | | 34 | | |
| Turn-on energy | E_{ON} | | | 114 | | |
| Turn-off energy | E_{OFF} | | | 31 | | |
| Total switching energy | E_{TOTAL} | | | 145 | | |

Typical Performance Diagrams

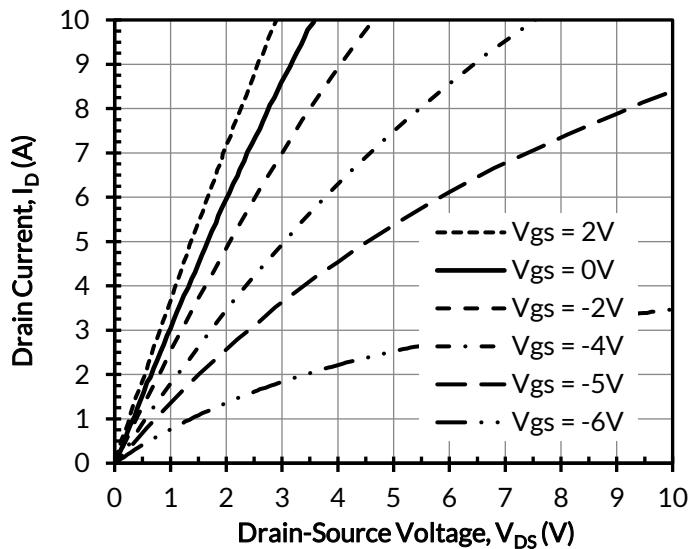


Figure 1. Typical output characteristics at $T_J = -55^\circ\text{C}$,
 $t_p < 250\mu\text{s}$

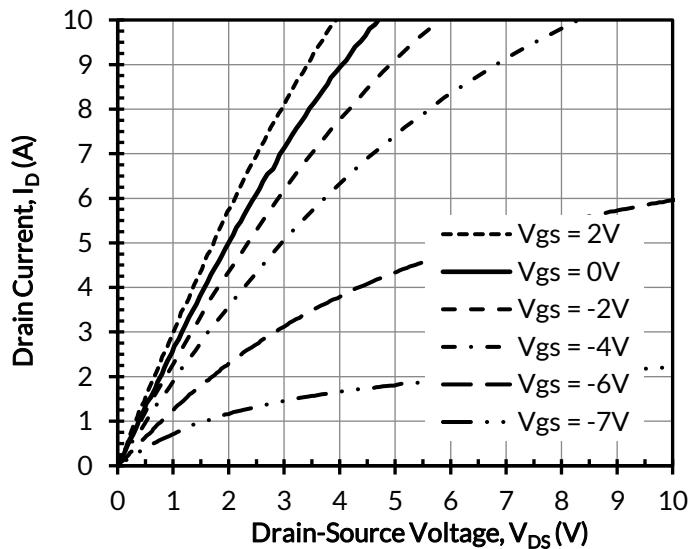


Figure 2. Typical output characteristics at $T_J = 25^\circ\text{C}$,
 $t_p < 250\mu\text{s}$

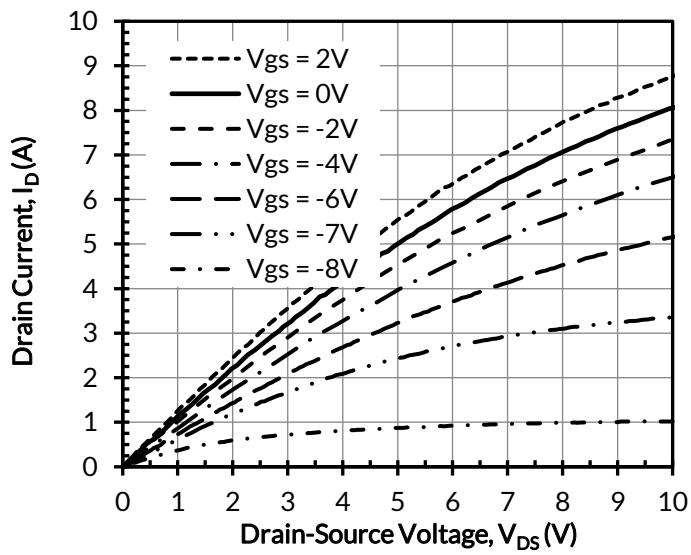


Figure 3. Typical output characteristics at $T_J = 175^\circ\text{C}$,
 $t_p < 250\mu\text{s}$

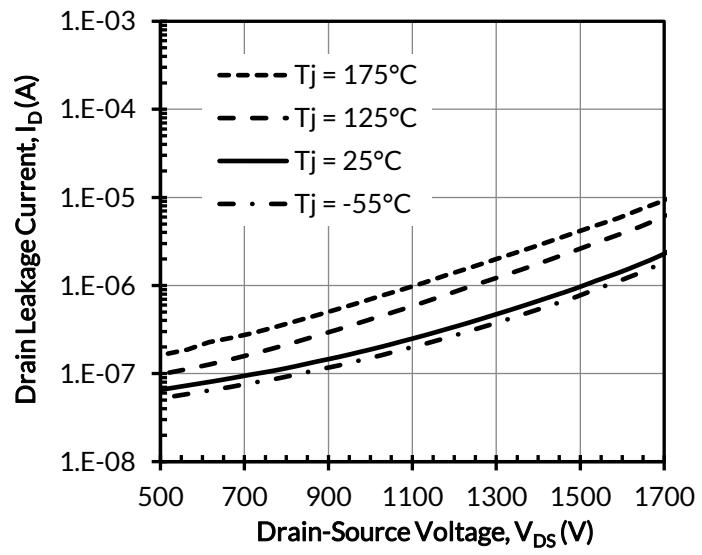


Figure 4. Typical drain-source leakage at $V_{GS} = -20\text{V}$

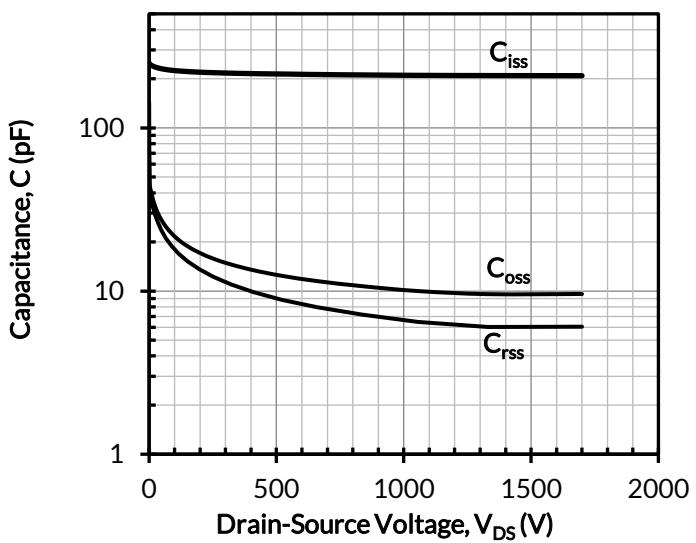


Figure 5. Typical capacitances at $f = 100\text{kHz}$ and $V_{GS} = -20\text{V}$

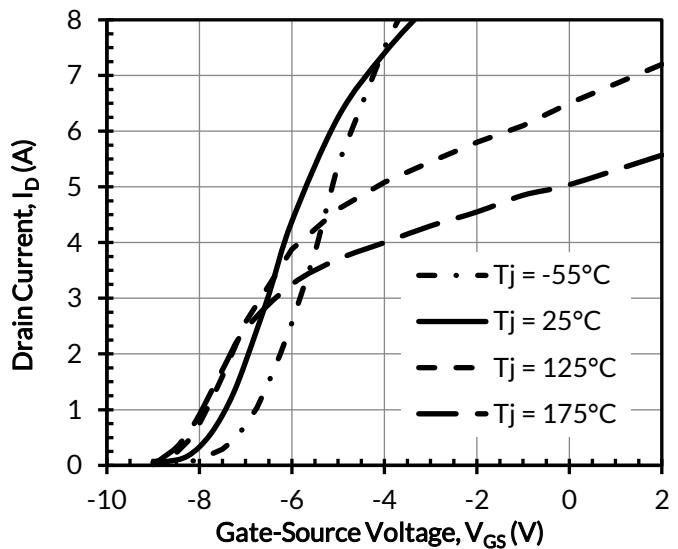


Figure 6. Typical transfer characteristics at $V_{DS} = 5\text{V}$

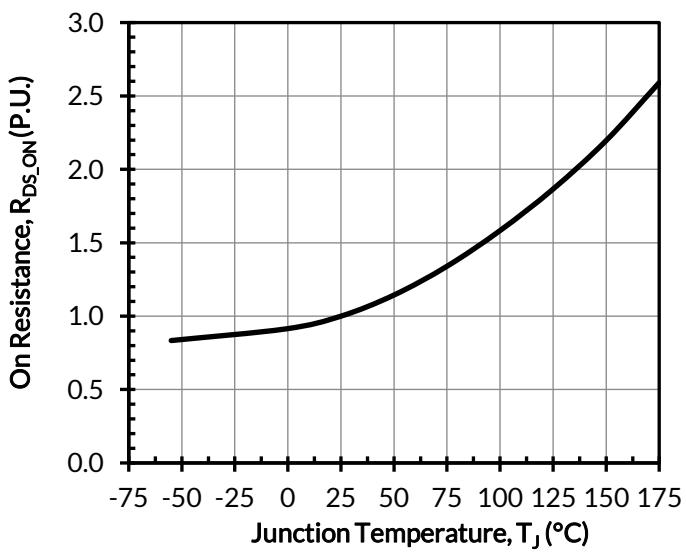


Figure 7. Normalized on-resistance vs. temperature at $V_{GS} = 0\text{V}$ and $I_D = 5\text{A}$

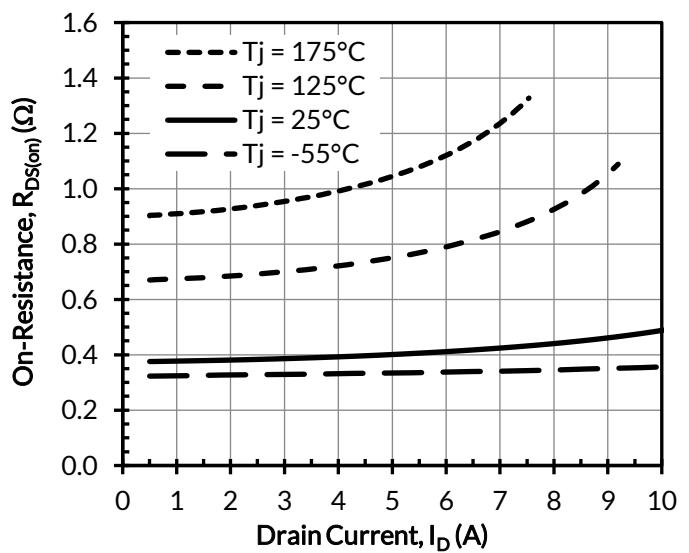


Figure 8. Typical drain-source on-resistances at $V_{GS} = 0\text{V}$

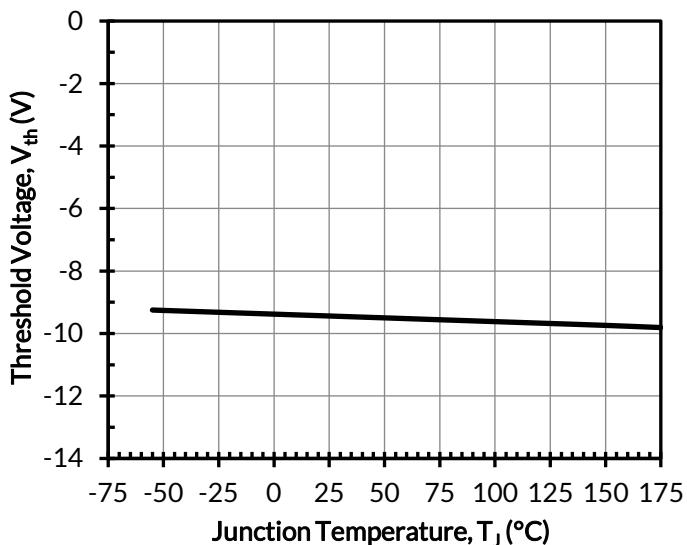


Figure 9. Threshold voltage vs. junction temperature at $V_{DS} = 5V$ and $I_D = 4.5mA$

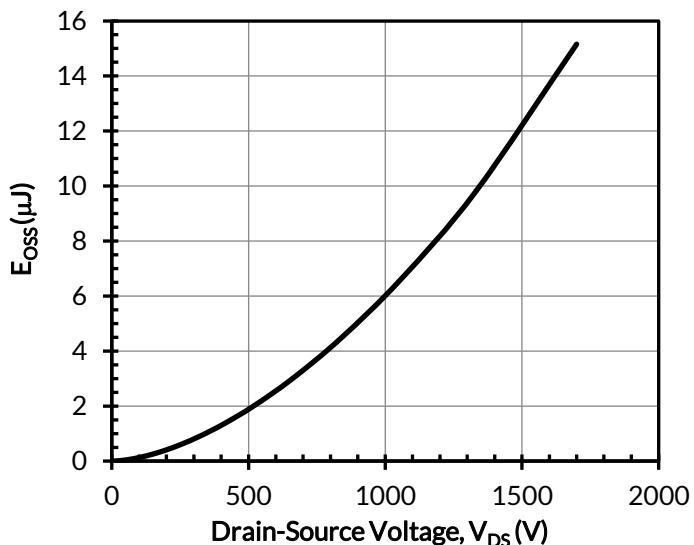


Figure 10. Typical stored energy in C_{OSS} at $V_{GS} = -20V$

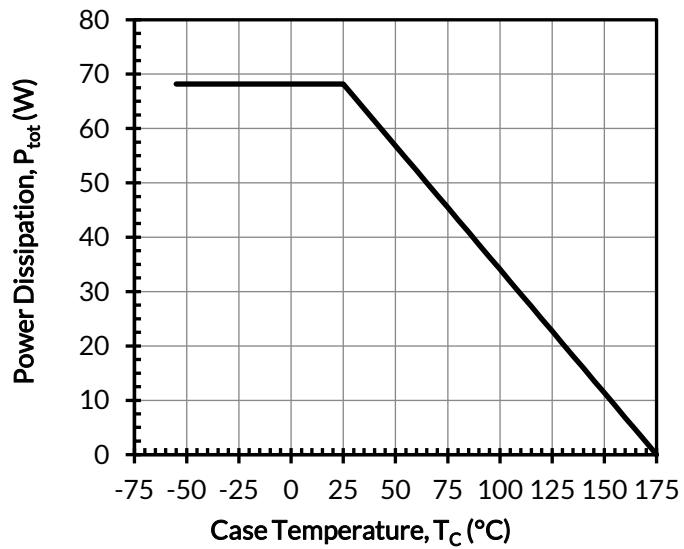


Figure 11. Total power Dissipation

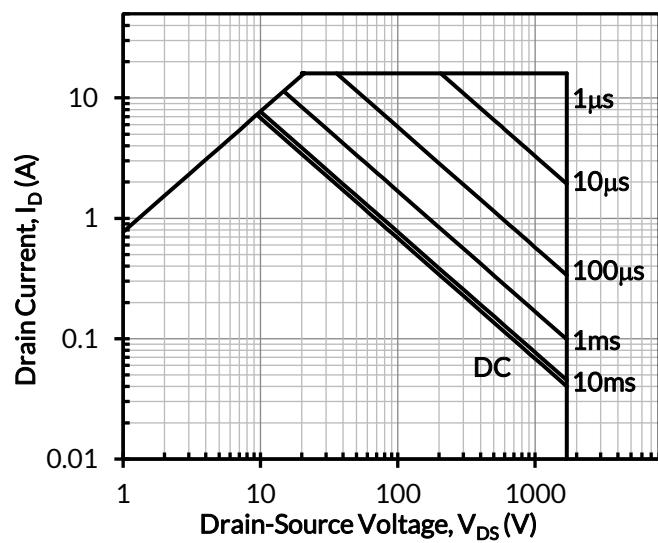


Figure 12. Safe operation area at $T_C = 25^\circ C$, Parameter t_p

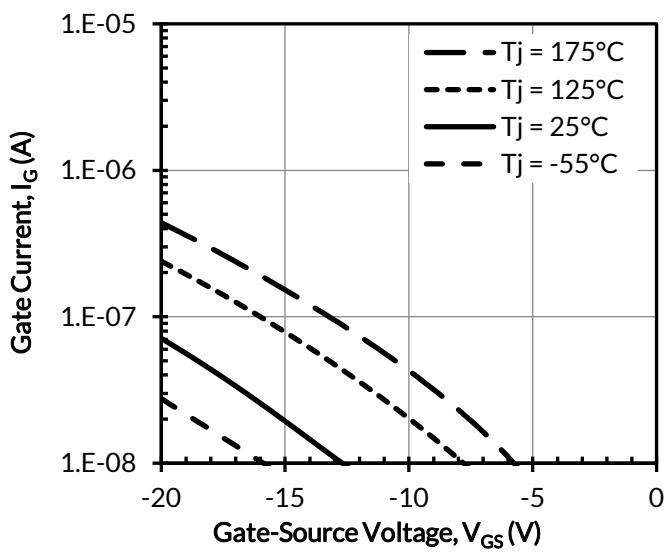


Figure 13. Typical gate leakage at $V_{DS} = 0V$

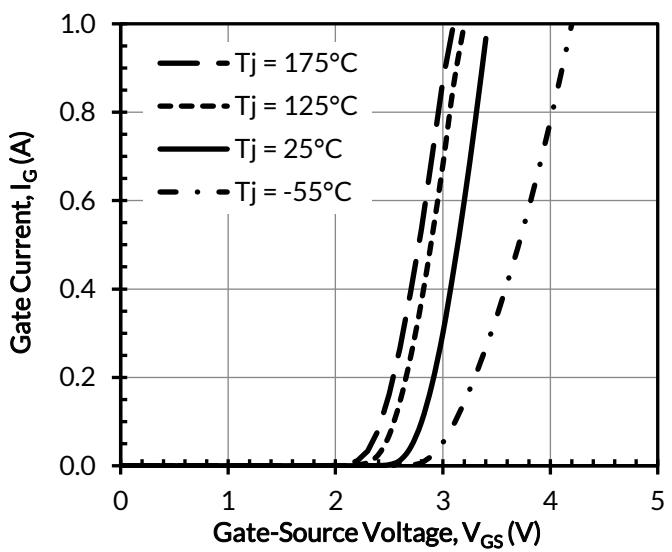


Figure 14. Typical gate forward current at $V_{DS} = 0V$

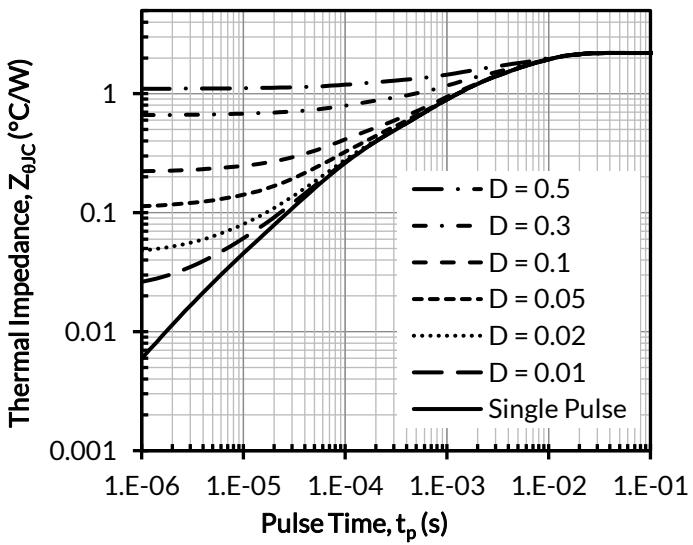


Figure 15. Maximum transient thermal impedance

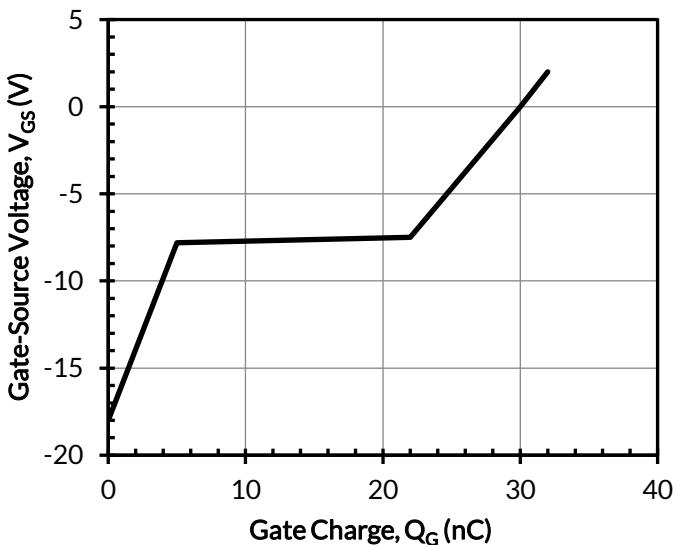


Figure 16. Typical gate charge at $V_{DS} = 1200V$ and $I_D = 5A$

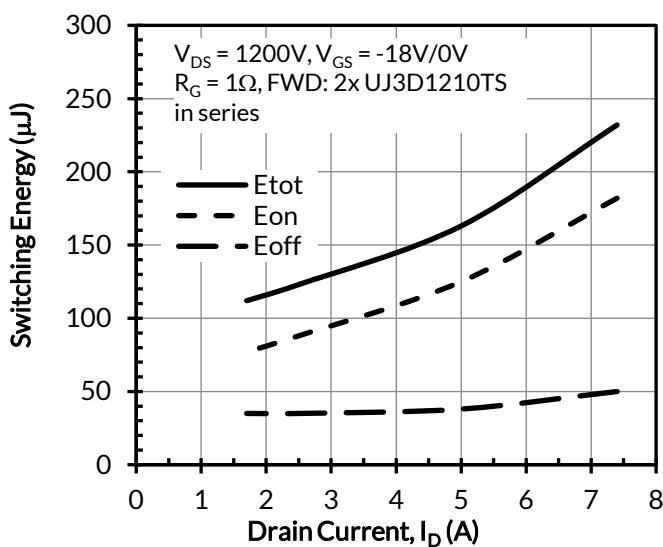


Figure 17. Clamped inductive switching energy vs. drain current at $T_J = 25^\circ C$

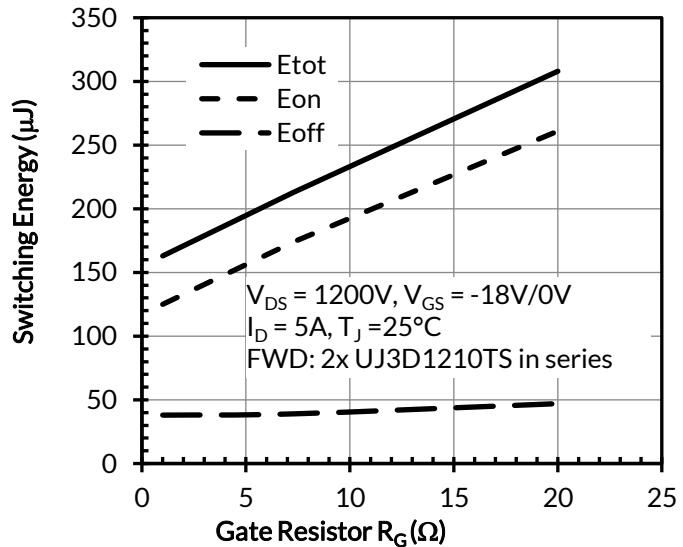


Figure 18. Clamped inductive switching energy vs. gate resistor R_G

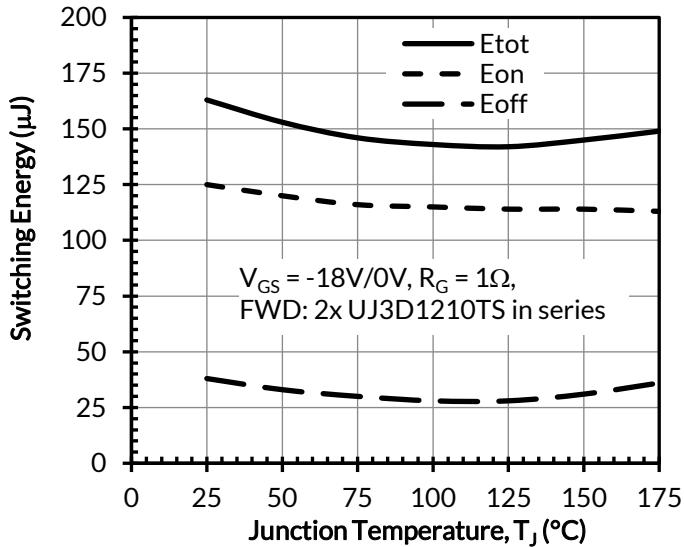


Figure 19. Clamped inductive switching energy vs. junction temperature at $V_{DS} = 1200V$ and $I_D = 5A$

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